What is claimed is:

1. A heat spreader comprising:

a body having a top surface, a bottom surface, at least one side and at least one corner;

a plurality of downset legs formed thereon, wherein the plurality of downset legs are formed to be downset from the body bottom surface by a distance, wherein the plurality of downset legs and the body bottom surface define a cavity; and

at least one notch formed between the top surface and the bottom surface proximate to the at least one corner.

2. The heat spreader of claim 1, wherein at least one downset leg is formed proximate to the at least one corner of the heat spreader body.

3. The heat spreader of claim 1, wherein at least one of the downset legs has a void formed therein, wherein the void is configured to receive at least one mechanical attachment device.

4. The heat spreader of claim 1, wherein the at least one downset leg is configured to receive at least one clip.

5. The heat spreader of claim 1, wherein the body and the at least one downset leg is comprised of thermally conductive material.

6. The heat spreader of claim 1, wherein the cavity is configured to receive at least one microelectronic die.

7. A method of forming a heat spreader comprising:

forming a mass of material approximately rectangular in shape; and

forming at least one downset leg on the mass of material.

8. The method of claim 7, wherein the forming comprises at least one cold forming process.

9. The method of claim 7, wherein the method further comprises forming at least one corner on the mass of material, wherein the at least one downset leg is formed in the vicinity of the corner.

10. The method of claim 7, wherein at least one void is formed on the at least one downset leg, wherein the void is configured to receive at least one mechanical attachment device.

11. The method of claim 7, wherein the at least one downset leg is formed to be configured to received at least one clamp.

12. A microelectronic package comprising:

a substrate having a surface;

at least one microelectronic die attached to the surface; and

a heat spreader attached to the surface, wherein the heat spreader has a top surface, a bottom surface, at least one side and at least one corner, wherein a plurality of downset legs is formed thereon, wherein the plurality of downset legs are formed to be downset from the bottom surface by a distance, and the plurality of downset legs and the bottom surface define a cavity, and at least one notch formed between the top surface and the bottom surface proximate to the at least one corner.

13. The microelectronic package of claim 12, wherein said microelectronic die is configured to be disposed within the cavity, and is configured to be attached to the bottom surface of the heat spreader.

14. The microelectronic package of claim 12, wherein at least one of the plurality of downset legs is formed in the vicinity of the corner of said heat spreader.

15. The microelectronic package of claim 12, wherein at least one of the plurality of downset legs has at least one void formed thereon, wherein the at least one void is configured to receive one or more mechanical attachment devices.

16. The microelectronic package of claim 12, wherein the at least one downset leg is configured to receive one or more clips.

17. The microelectronic package of claim 12, wherein the heat spreader is comprised of thermally conductive material.

18. The microelectronic package of claim 12, wherein the top surface is approximately octagonal in shape.

19. A computing system comprising:

a microelectronic package, which includes a substrate having a surface;

at least one microelectronic die attached to the surface; and

a heat spreader attached to the surface, wherein the heat spreader has a top surface, a bottom surface, at least one side and at least one corner, wherein a plurality of downset legs is formed thereon, wherein the plurality of downset legs are formed to be downset from the bottom

surface by a distance, and the plurality of downset legs and the bottom surface define a cavity, and at least one notch formed between the top surface and the bottom surface proximate to the at least one corner.

20. The computing system of claim 19, wherein the microelectronic die is configured to be disposed within the cavity, and is configured to be attached to the bottom surface of the heat spreader.

21. The computing system of claim 19, wherein at least one of the plurality of downset legs is formed in the vicinity of the corner of said heat spreader.

22. The computing system of claim 19, wherein at least one of the plurality of downset legs has at least one void formed thereon, wherein the at least one void is configured to receive one or more mechanical attachment devices.

23. The computing system of claim 19, wherein the at least one downset leg is configured to receive one or more clips.

24. The computing system of claim 19, wherein the heat spreader is comprised of thermally conductive material.

25. The computing system of claim 19, wherein the top surface is approximately octagonal in shape.